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Application Serial No.: 10/619,567
Yasuji HIRAMATSU, et al.

IN THE CLAIMS

Please amend the claims as follows:

1-4. (Canceled)

5. (New) A ceramic heater comprising a ceramic substrate in a disc form having a resistance heating element formed inside thereof or on the surface thereof, wherein said ceramic substrate has a straight notch.

6. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate has plural straight notches.

7. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate has an electrostatic electrode formed inside thereof; and functions as an electrostatic chuck.

8. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate has a through hole into which a lifter pin is inserted.

9. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

10. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate has a thickness of 20 mm or less.

11. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate has a diameter of 250 mm or more.

12. (New) The ceramic heater according to Claim 6, wherein said straight notches are evenly formed at a circumferential rim portion of said ceramic substrate.

13. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate is prevented from rotating by a contact of said notch with a rotation-blocking pin.

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14. (New) The ceramic heater according to Claim 5, wherein said ceramic substrate fitted into a supporting case and a rotation-blocking pin is inserted into said supporting case.

15. (New) A ceramic substrate having a conductor layer formed inside thereof or on the surface thereof,

wherein said ceramic substrate has a notch,

a chuck top conductor layer on the surface thereof, a guard electrode and/or a ground electrode inside thereof; and

said ceramic substrate functions as a wafer prober.

16. (New) The ceramic substrate according to Claim 15, wherein said ceramic substrate has a through hole into which a lifter pin is inserted.

17. (New) The ceramic substrate according to Claim 15, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

18. (New) The ceramic substrate according to Claim 15, wherein said ceramic substrate has a thickness of 20 mm or less.

19. (New) The ceramic substrate according to Claim 15, wherein said ceramic substrate has a diameter of 250 mm or more.